

Sawing device and method for forming saw-cuts into a semiconductor product

Abstract

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The invention relates to a sawing device for forming saw-cuts into a semiconductor product, comprising: a carrier for holding the semiconductor product, a saw blade, a first position sensor for determining the position of the semiconductor product held by the carrier, a second position sensor for determining the position of the saw
10 blade, and a control unit configured for controlling the relative movement of the saw blade and the carrier, wherein the sawing device further comprises a reference for linking the position of the first position sensor to the position of the second position sensor, wherein the control unit is configured to process, with aid of the reference, the positions determined by the reference sensors into a position of the point on the
15 free surface of the semiconductor product relative to the point on the cutting edge of the saw blade, and, based on this positional information, control the relative movement of the saw blade and the carrier. The invention further relates to a method for forming saw-cuts into a semiconductor product.

20 [Figure 1]